NESTED INTERPOSER PACKAGE FOR IC CHIPS

ABSTRACT

Embodiments disclosed herein include electronic packages and methods of forming electronic packages. In an embodiment, an electronic package comprises an interposer, where the interposer comprises a cavity that passes through the interposer, a through interposer via (TIV), and an interposer pad electrically coupled to the TIV. In an embodiment, the electronic package further comprises a nested component in the cavity, where the nested component comprises a component pad, and a die coupled to the interposer pad by a first interconnect and coupled to the component pad by a second interconnect. In an embodiment, the first interconnect and the second interconnect each comprise an intermediate pad, and a bump over the intermediate pad.

Fig. 1A